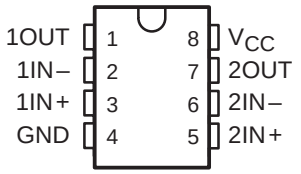
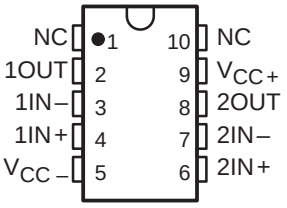
- **Very Low Power Consumption**
- **Power Dissipation With ±2-V Supplies 170 μW Typ**
- **Low Input Bias and Offset Currents**
- **Output Short-Circuit Protection**
- **Low Input Offset Voltage**
- **Internal Frequency Compensation**
- **Latch-Up-Free Operation**
- **Popular Dual Operational Amplifier Pinout**

TL022M . . . JG PACKAGE
TL022C . . . D OR P PACKAGE
(TOP VIEW)



TL022M . . . U PACKAGE
(TOP VIEW)

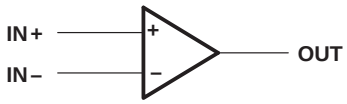


TL022M IS NOT RECOMMENDED FOR NEW DESIGNS

description

The TL022 is a dual low-power operational amplifier designed to replace higher power devices in many applications without sacrificing system performance. High input impedance, low supply currents, and low equivalent input noise voltage over a wide range of operating supply voltages result in an extremely versatile operational amplifier for use in a variety of analog applications including battery-operated circuits. Internal frequency compensation, absence of latch-up, high slew rate, and output short-circuit protection assure ease of use.

symbol (each amplifier)



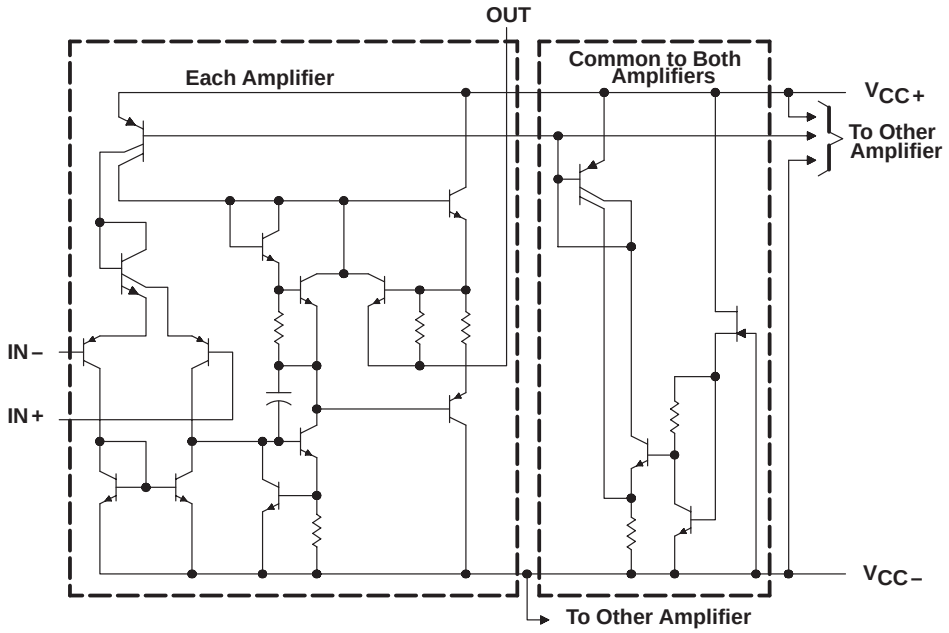
The TL022C is characterized for operation from 0°C to 70°C. The TL022M is characterized for operation over the full military temperature range of –55°C to 125°C.

AVAILABLE OPTIONS

T_A	V_{IO}max AT 25°C	PACKAGE			
		SMALL OUTLINE (D)	CERAMIC DIP (JG)	PLASTIC DIP (P)	CERAMIC FLAT PACK (U)
0°C to 70°C	5 mV	TL022CD	—	TL022CP	—
–55°C to 125°C	5 mV	—	TL022MJG	—	TL022MU

The D package is available taped and reeled. Add the suffix R to the device type (i.e. TL022CDR).

schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		TL022C	TL022M	UNIT
Supply voltage, V_{CC+} (see Note 1)		18	22	V
Supply voltage, V_{CC-} (see Note 1)		–18	–22	V
Differential input voltage (see Note 2)		±30	±30	V
Input voltage (any input, see Notes 1 and 3)		±15	±15	V
Duration of output short circuit (see Note 4)		unlimited	unlimited	
Continuous total dissipation		See Dissipation Rating Table		
Operating free-air temperature range		0 to 70	–55 to 125	°C
Storage temperature range		–65 to 150	–65 to 150	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	JG or U package		300	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D or P package	260		°C

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN–.
3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
4. The output may be shorted to ground or either power supply. For the TL022M only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 75°C free-air temperature.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	680 mW	5.8 mW/°C	33°C	464 mW	—
JG	680 mW	8.4 mW/°C	69°C	672 mW	210 mW
P	680 mW	8.0 mW/°C	65°C	640 mW	—
U	675 mW	5.4 mW/°C	25°C	432 mW	135 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC+}	5	15	V
Supply voltage, V_{CC-}	−5	−15	V

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL022C			TL022M			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0, R_S = 50 Ω	25°C		1	5		1	5	mV
			Full range			7.5			6	
I_{IO}	Input offset current	V_O = 0	25°C		15	80		5	40	nA
			Full range			200			100	
I_{IB}	Input bias current	V_O = 0	25°C		100	250		50	100	nA
			Full range			400			250	
V_{ICR}	Common-mode input voltage range		25°C	±12	±13		±12	±13		V
			Full range	±12			±12			
$V_{O(PP)}$	Maximum peak-to-peak output voltage swing	R_L = 10 kΩ	25°C	20	26		20	26		V
		R_L ≥ 10 kΩ	Full range	20			20			
A_{VD}	Large-signal differehtial voltage amplification	R_L ≥ 10 kΩ, V_O = ±10 V	25°C	60	80		72	86		dB
			Full range	60			66			
B_1	Unity-gain bandwidth		25°C		0.5			0.5		MHz
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, R_S = 50 Ω	25°C	60	72		60	72		dB
			Full range	60			60			
k_{SVS}	Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	V_{CC} = ± 9 V to ±15 V, R_S = 50 Ω	25°C		30	200		30	150	μV/V
			Full range			200			150	
V_n	Equivalent input noise voltage	A_{VD} = 20 dB, B = 1 Hz, f = 1 kHz	25°C		50			50		nV/Hz
I_{OS}	Short-circuit output current		25°C		±6			±6		mA
I_{CC}	Supply current (both amplifiers)	V_O = 0, No load	25°C		130	250		130	250	μA
			Full range			250			250	
P_D	Total dissipation (both amplifiers)	V_O = 0, No load	25°C		3.9	7.5		3.9	6	mW
			Full range			7.5			6	

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for TL022C is 0°C to 70°C and for TL022M is −55°C to 125°C.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_r	Rise time	V_I = 20 mV, R_L = 10 kΩ, C_L = 100 pF, See Figure 1		0.3		μs
	Overshoot factor			5%		
SR	Slew rate at unity gain	V_I = 10 V, R_L = 10 kΩ, C_L = 100 pF, See Figure 1		0.5		V/μs

PARAMETER MEASUREMENT INFORMATION

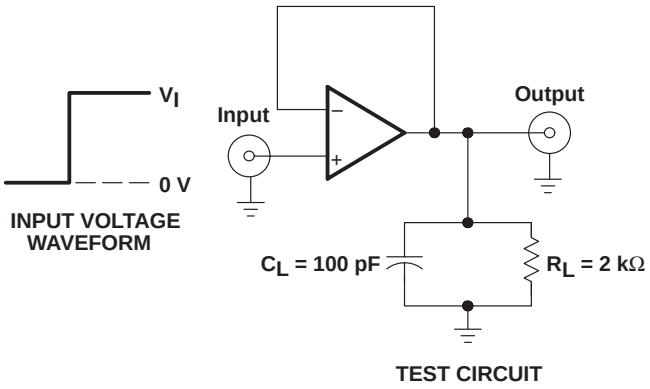


Figure 1. Rise Time, Overshoot Factor, and Slew Rate

TYPICAL CHARACTERISTICS

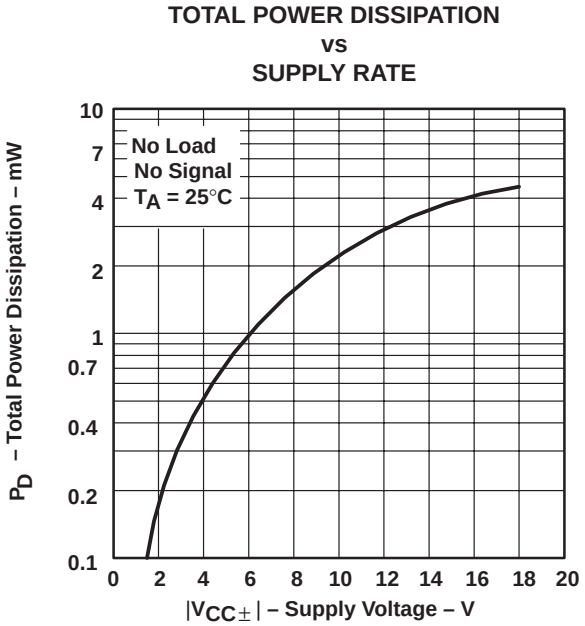


Figure 2

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL022CD	Obsolete	Production	SOIC (D) | 8	-	-	Call TI	Call TI	0 to 70	TL022C
TL022CDR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDR.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDR.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDR.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C
TL022CDRG4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	-	Call TI	Call TI	0 to 70	
TL022CDRG4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	-	Call TI	Call TI	0 to 70	
TL022CDRG4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	-	Call TI	Call TI	0 to 70	
TL022CP	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CP	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CP	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CP.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CP.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CP.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL022CP
TL022CPSR	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSR	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSR	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSR.A	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSR.A	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSR.A	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSRG4	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSRG4	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022
TL022CPSRG4	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T022

(1) **Status:** For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

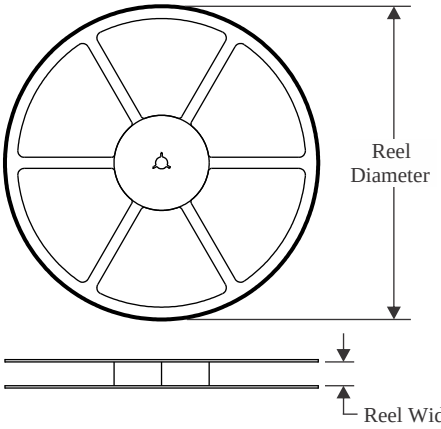
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

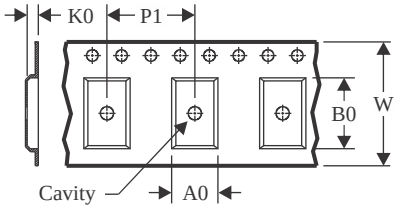
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

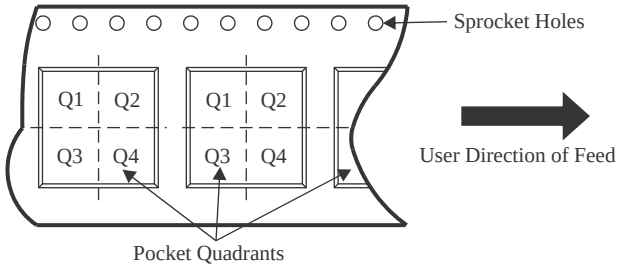


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

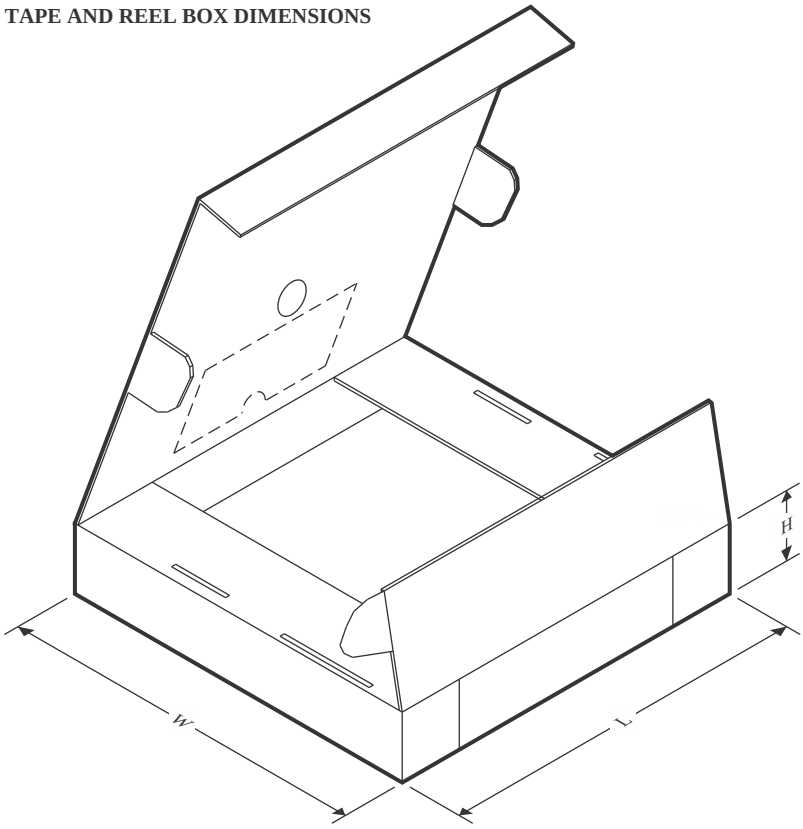
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL022CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL022CPSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1

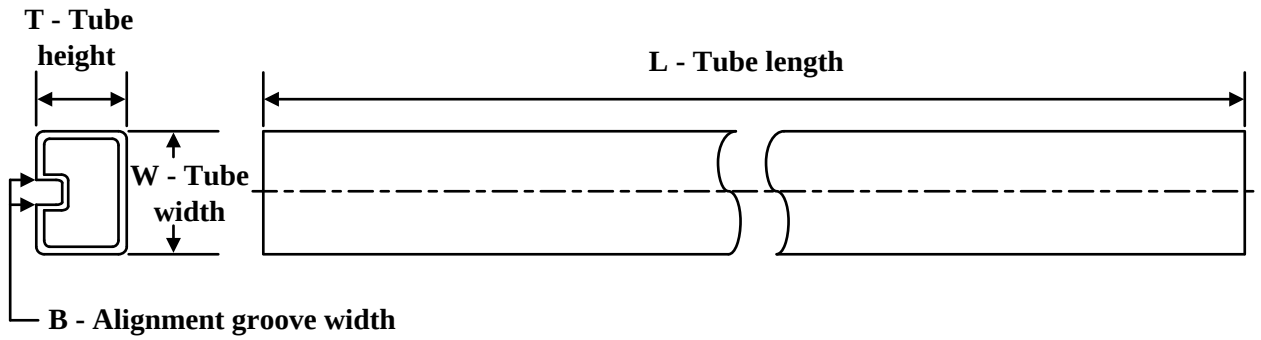
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

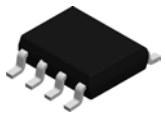
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL022CDR	SOIC	D	8	2500	353.0	353.0	32.0
TL022CPSR	SO	PS	8	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL022CP	P	PDIP	8	50	506	13.97	11230	4.32
TL022CP.A	P	PDIP	8	50	506	13.97	11230	4.32

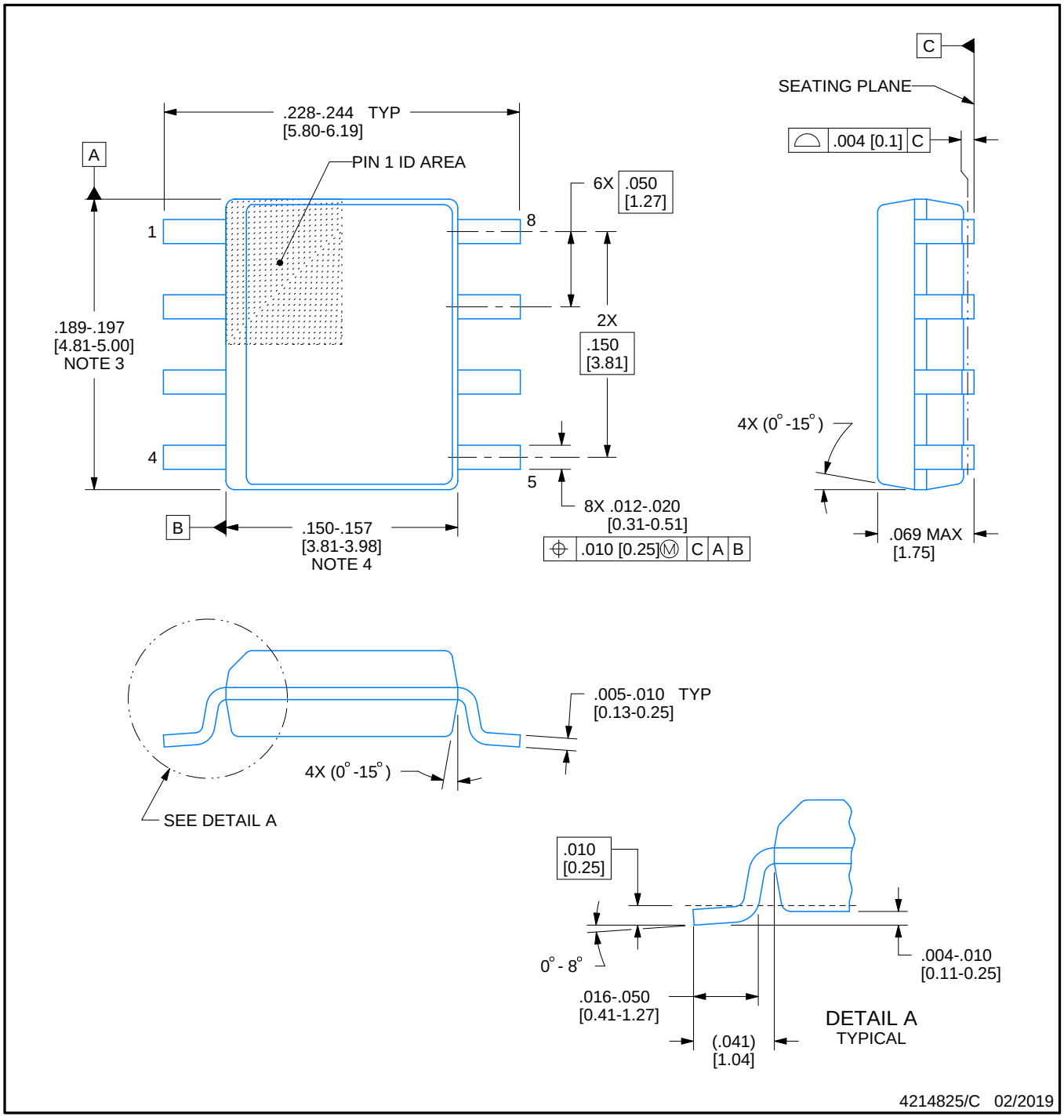


PACKAGE OUTLINE

D0008A

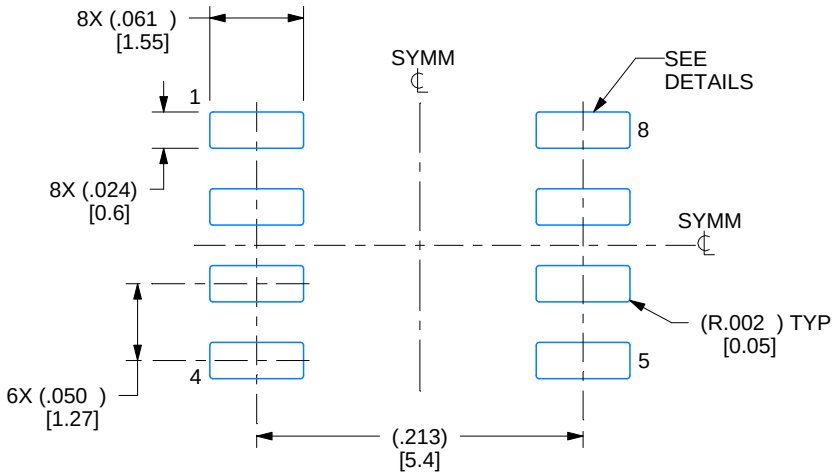
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

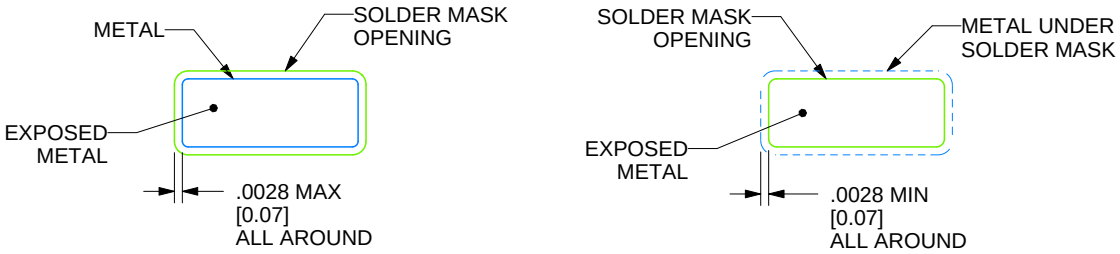


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

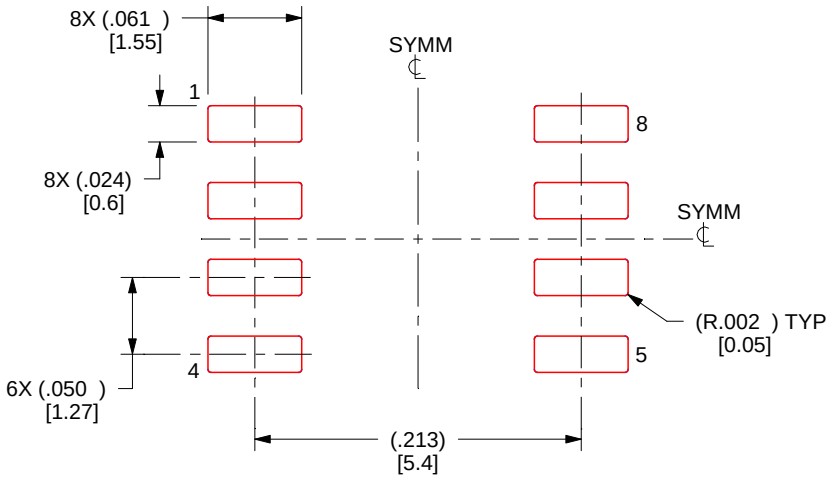
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

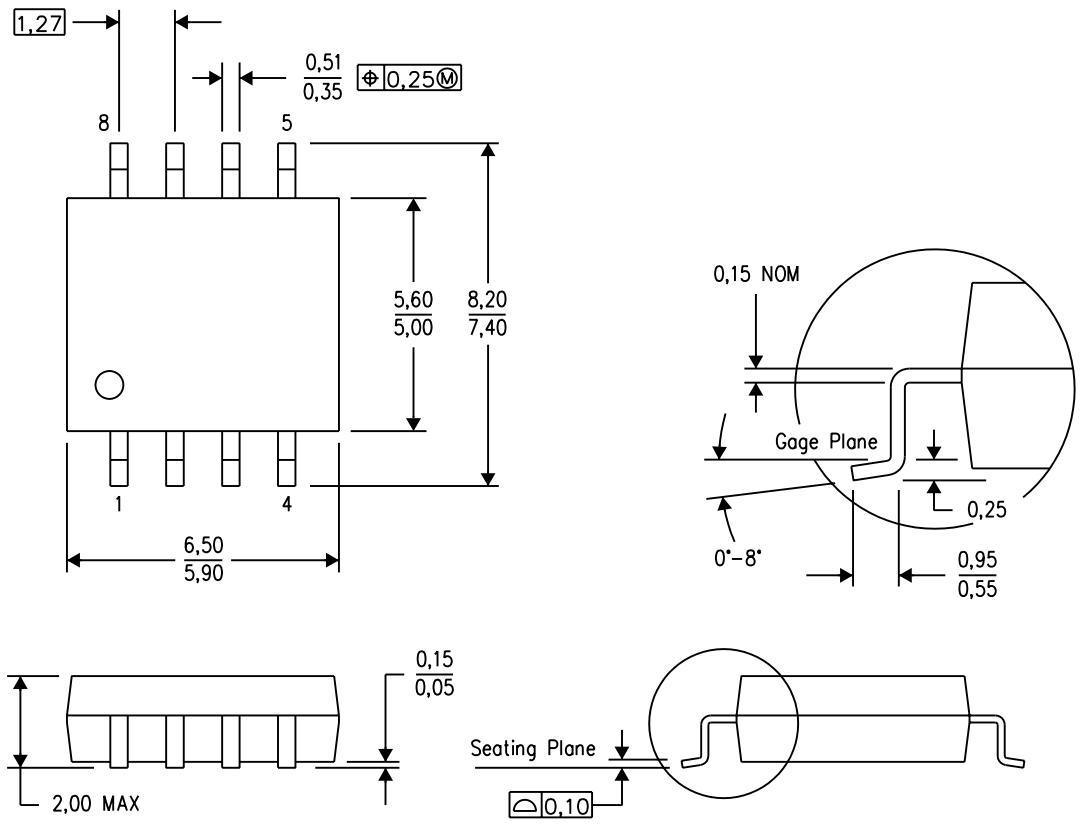
4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

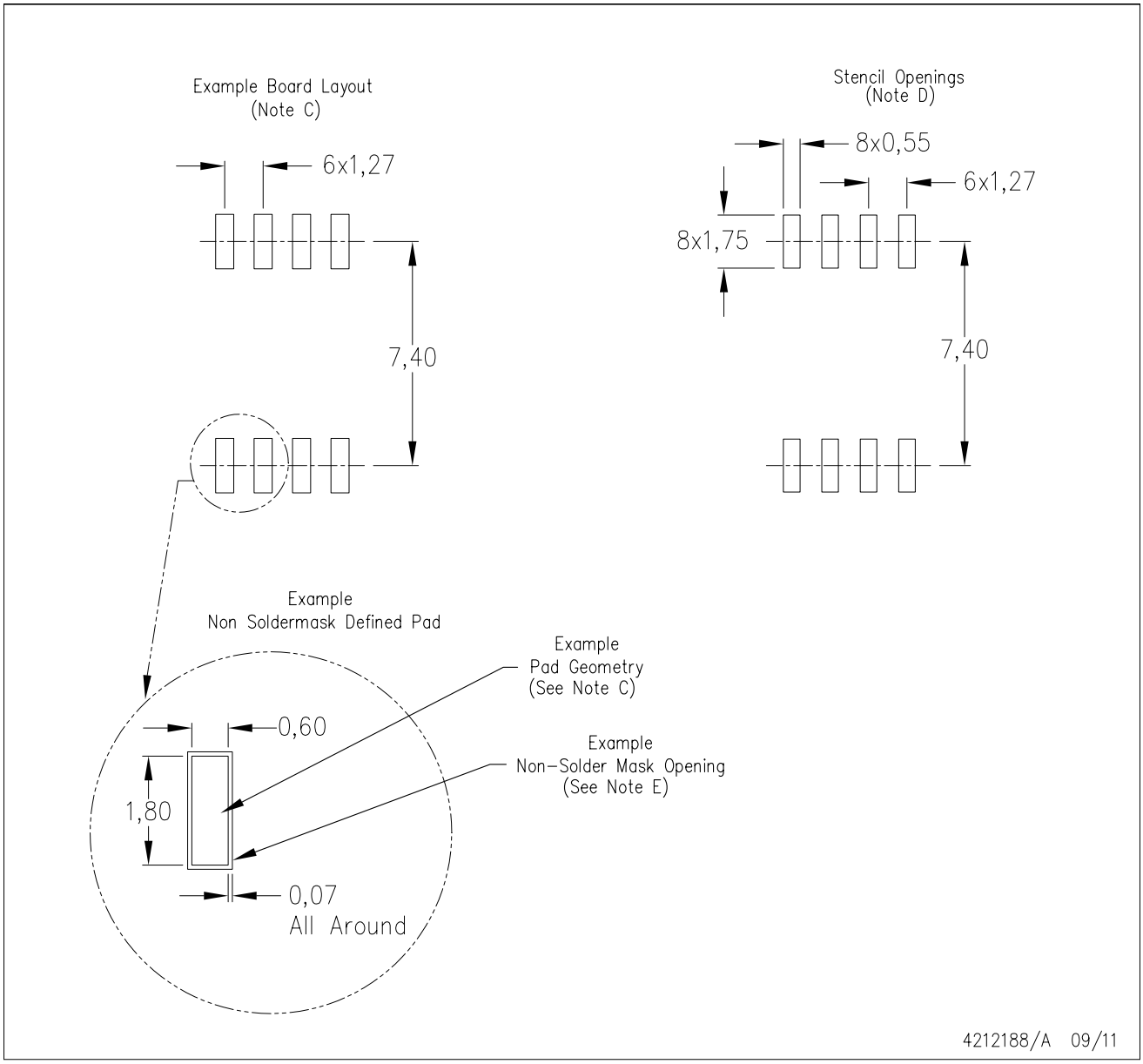
PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

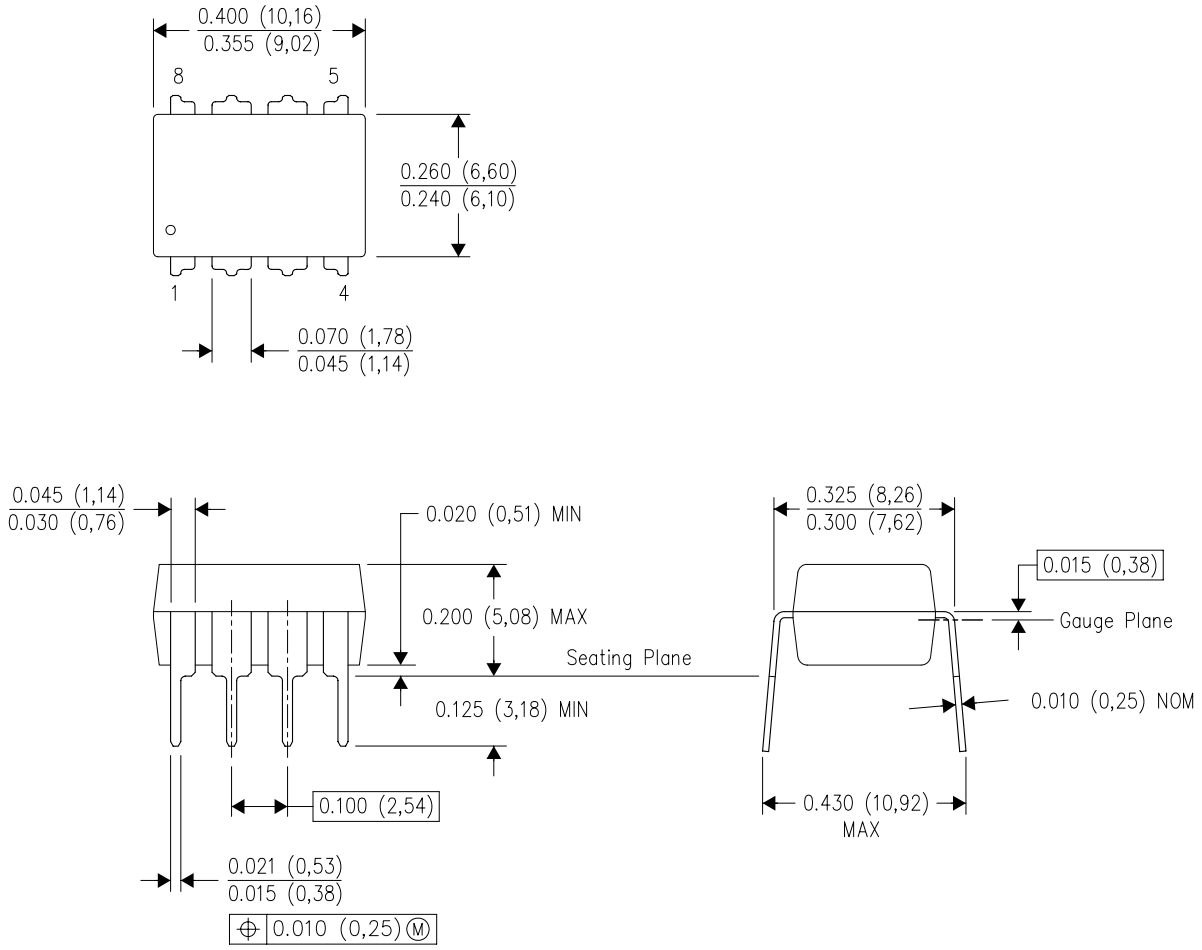
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Last updated 10/2025